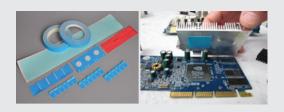


Technical Data Sheet

EverTherm EVSA416FG thermal tape is widely used to bond heat sinks to microprocessors and other power consuming semiconductors. It has outstanding bonding strength and low thermal impedance making it the perfect choice to effectively replace silicone grease and any type of mechanical fixturing.



Material Properties

- High-strength viscosity suitable for many surfaces
- •Double-sided pressure-sensitive adhesive tape
- High thermally conductive acrylic adhesive
- Will not breakdown under continuous high tempreature

Applications

- ✓ LED lighting products
- ♥ Chassis, frame or other cooling
- componentsLarge capacity drive
- ✓ Heat pipe assembly
- ∀ High frequency micro processing chip
- ✓ Notebook and desktop computers



EVSA416FG

Color	White	Visual
Substrate	Acrylicresin (Acrylic)	***
Substrate reinforcement	Fiberglass	***
Thickness(mm)	0.40±0.02	ASTM D374
Dielectric Breakdown Voltageh@AC	>5000V	ASTM D149
Release force (kg/mm)	2.5/25	PSTC-3
Stickiness (KG/ weight)/ time 48H	1.0	***
Initial viscosity (ball)	≥14#	***
Shear strength1.0 kg loading on 25 mm x 25 mm	> 48 hrs	PSTC-7
Heat resistance0.5kg loading on 25mm x 25mm at 80°C	> 24 hrs	***
Thermal conductivity (W/m-k)	<0.2	ASTM D5470
Operating temperature	-30 ~130	***
Shelf Life	6 month	***
Life Time	36 month	***
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

CR Technology, Inc

- 55 Chase St. Methuen, Massachusetts 01844
- sales@crtechinc.com
- 978.681.5300

Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.